

BGM210L Blue Gecko Bluetooth® Lighting Module Data Sheet



The BGM210L is a module designed and built to meet the performance, security, and reliability requirements of line-powered, smart LED lighting products.

Based on the EFR32BG21 Blue Gecko SoC, it enables Bluetooth 5.1 and Bluetooth Mesh connectivity delivering best-in-class RF performance, CA Title 20 energy consumption compliance, future-proof capability for feature and OTA firmware updates, enhanced security, and a form factor and temperature rating suited for enclosed operation in lightbulb housings.

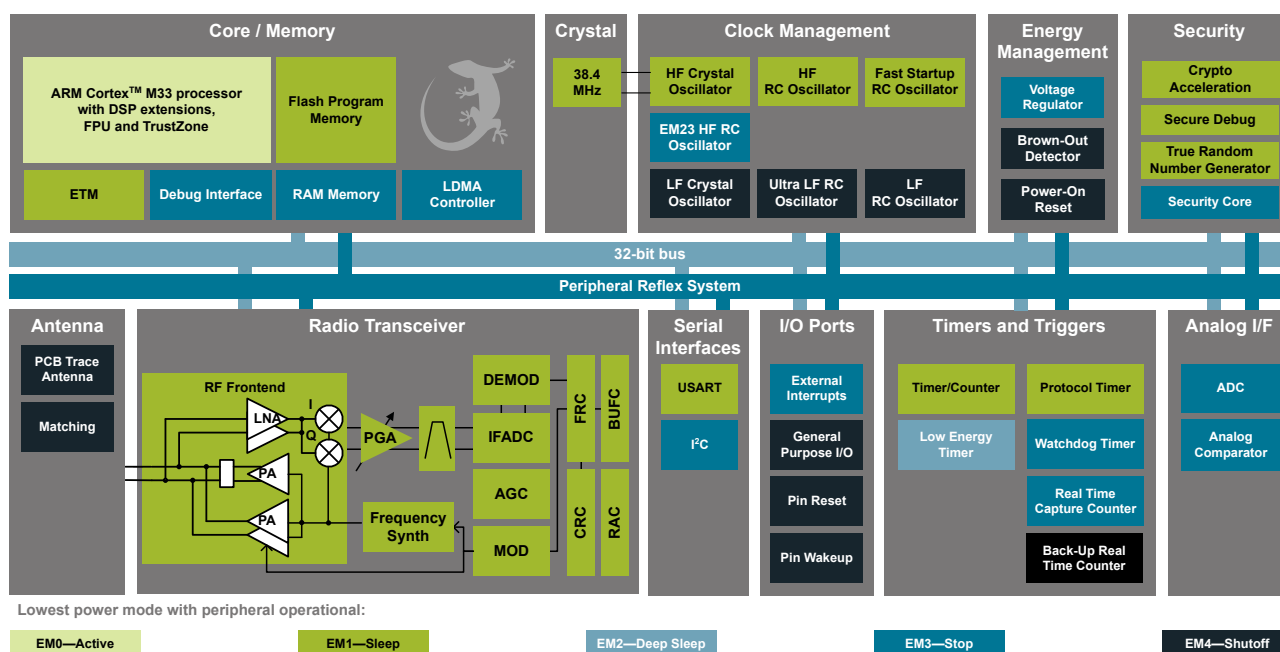
The BGM210L is a complete solution that comes with fully-upgradeable, robust software stacks, world-wide regulatory certifications, advanced development and debugging tools, and support that will simplify and minimize the development cycle of your product helping to accelerate its time-to-market.

The BGM210L is targeted for key applications that include:

- Smart LED lightbulbs
- Connected lighting

KEY FEATURES

- Bluetooth 5.1 and Bluetooth Mesh connectivity
- PCB Trace antenna
- +12.5 dBm Max TX power
- -97 dBm Bluetooth RX sensitivity @ 1 Mbps
- 32-bit ARM Cortex-M33 core at 38.4 MHz
- 1024/96 kB of flash/RAM memory
- Enhanced security features
- Optimal set of MCU peripherals
- 12 GPIO pins
- -40 to (105 or 125)°C
- 15.5 mm x 22.5 mm (custom form factor)



1. Features

- **Supported Protocols**
 - Bluetooth 5.1
 - AoA/AoD
 - Bluetooth Mesh
- **Wireless System-on-Chip**
 - 2.4 GHz radio
 - TX power up to +12.5 dBm
 - 32-bit ARM Cortex®-M33 with DSP instruction and floating-point unit for efficient signal processing
 - 1024 kB flash program memory
 - 96 kB RAM data memory
 - Embedded Trace Macrocell (ETM) for advanced debugging
- **Receiver Performance**
 - -104.4 dBm sensitivity (0.1% BER) at 125 kbps GFSK
 - -100.1 dBm sensitivity (0.1% BER) at 500 kbps GFSK
 - -97 dBm sensitivity (0.1% BER) at 1 Mbps GFSK
 - -93.9 dBm sensitivity (0.1% BER) at 2 Mbps GFSK
- **Current Consumption**
 - 9.3 mA RX current at 1 Mbps GFSK
 - 70 mA TX current at +12.5 dBm output power
 - 50.9 µA/MHz in Active Mode (EM0)
 - 5.1 µA EM2 DeepSleep current (RTCC running from LFXO, Bluetooth Stack not running)
 - 8.5 µA EM2 DeepSleep current (RTCC running from LFXO, Bluetooth Stack running)
- **Regulatory Certifications**
 - CE
 - ISED
 - FCC
 - Australia
 - Dominican Republic
 - Hong Kong
 - Israel
 - Jordan
 - Kuwait
 - Serbia
 - Singapore
- **Operating Range**
 - 1.8 to 3.8 V
 - -40 to +105 °C or -40 to +125 °C
- **Dimensions**
 - 15.5 mm x 22.5 mm (custom form factor)
- **Security**
 - Secure Boot with Root of Trust and Secure Loader (RTSL)¹
 - Hardware Cryptographic Acceleration with DPA counter-measures¹ for AES128/256, SHA-1, SHA-2 (up to 256-bit), ECC (up to 256-bit), ECDSA, and ECDH
 - True Random Number Generator (TRNG) compliant with NIST SP800-90 and AIS-31
 - ARM® TrustZone®
 - Secure Debug Interface lock/unlock
- **MCU Peripherals**
 - 12-bit 1 Msps SAR Analog to Digital Converter (ADC)
 - 2 × Analog Comparator (ACMP)
 - 12 General Purpose I/O pins with output state retention and asynchronous interrupts
 - 8 Channel DMA Controller
 - 12 Channel Peripheral Reflex System (PRS)
 - 2 × 16-bit Timer/Counter (3 Compare/Capture/PWM channels)
 - 1 × 32-bit Timer/Counter (3 Compare/Capture/PWM channels)
 - 32-bit Real Time Counter
 - 24-bit Low Energy Timer for waveform generation
 - 2 × Watchdog Timer
 - 3 × Universal Synchronous/Asynchronous Receiver/Transmitter (UART/SPI/SmartCard (ISO 7816)/IrDA/I²S)
 - 2 × I²C interface with SMBus support

1. With Secure Element (SE) firmware v1.1.2 or newer

2. Ordering Information

Table 2.1. Ordering Information

Ordering Code	Protocol Stack	Max TX Power	Freq Band	Antenna	Flash (kB)	RAM (kB)	GPIO	Temp Range	Packaging
BGM210LA22JIF2	• Bluetooth 5.1	12.5 dBm	2.4 GHz	Inverted-F PCB Trace	1024	96	12	-40 to 125 °C	Cut Tape
BGM210LA22JIF2R	• Bluetooth 5.1	12.5 dBm	2.4 GHz	Inverted-F PCB Trace	1024	96	12	-40 to 125 °C	Reel
BGM210LA22JNF2	• Bluetooth 5.1	12.5 dBm	2.4 GHz	Inverted-F PCB Trace	1024	96	12	-40 to 105 °C	Cut Tape
BGM210LA22JNF2R	• Bluetooth 5.1	12.5 dBm	2.4 GHz	Inverted-F PCB Trace	1024	96	12	-40 to 105 °C	Reel

End-product manufacturers must verify that the module is configured to meet regulatory limits for each region in accordance with the formal certification test reports.

Devices are pre-programmed with BGAPI UART DFU bootloader.

SLWRB4309B radio board is available for BGM210L evaluation and development.

Table of Contents

1. Features	2
2. Ordering Information	3
3. System Overview	6
3.1 Block Diagram	6
3.2 EFR32BG21 SoC	6
3.3 Antenna	6
3.4 Power Supply	6
4. Electrical Specifications	7
4.1 Electrical Characteristics	7
4.1.1 Absolute Maximum Ratings	7
4.1.2 General Operating Conditions	8
4.1.3 MCU Current Consumption at 3.0V	9
4.1.4 Radio Current Consumption at 3.0V	10
4.1.5 RF Transmitter General Characteristics for the 2.4 GHz Band	11
4.1.6 RF Receiver General Characteristics for the 2.4 GHz Band	11
4.1.7 RF Receiver Characteristics for Bluetooth Low Energy at 1 Mbps	12
4.1.8 RF Receiver Characteristics for Bluetooth Low Energy at 2 Mbps	13
4.1.9 RF Receiver Characteristics for Bluetooth Low Energy at 500 kbps	14
4.1.10 RF Receiver Characteristics for Bluetooth Low Energy at 125 kbps	15
4.1.11 High-Frequency Crystal	16
4.1.12 GPIO Pins	16
4.1.13 Microcontroller Peripherals	17
4.2 Typical Performance Curves	17
4.2.1 Antenna Radiation and Efficiency	18
5. Reference Diagrams	19
6. Pin Definitions	20
6.1 Module Pinout	20
6.2 Alternate Pin Functions	21
6.3 Analog Peripheral Connectivity	21
6.4 Digital Peripheral Connectivity	22
7. Design Guidelines	25
7.1 Module Placement	25
7.2 Antenna	26
8. Package Specifications	27
8.1 Dimensions	27
8.2 PCB Land Pattern	28
8.3 Marking	29

9. Soldering Recommendations 30

10. Tape and Reel 31

11. Certifications 32

11.1 CE 32

11.2 FCC 32

11.3 ISED Canada 33

11.4 Australia 34

11.5 Dominican Republic. 34

11.6 Hong Kong. 35

11.7 Israel. 35

11.8 Jordan 35

11.9 Kuwait 35

11.10 Serbia 35

11.11 Singapore. 35

12. Revision History. 36

3. System Overview

3.1 Block Diagram

The BGM210L module is a highly-integrated, high-performance system with all the hardware components needed to enable 2.4 GHz wireless connectivity and support robust networking capabilities via multiple protocols.

Built around the EFR32BG21 Wireless Gecko SoC, the BGM210L includes a built-in PCB trace antenna, an RF matching network (optimized for transmit power efficiency), supply decoupling and filtering components, a 38.4 MHz reference crystal, and an RF shield. A general block diagram of the module is shown below.

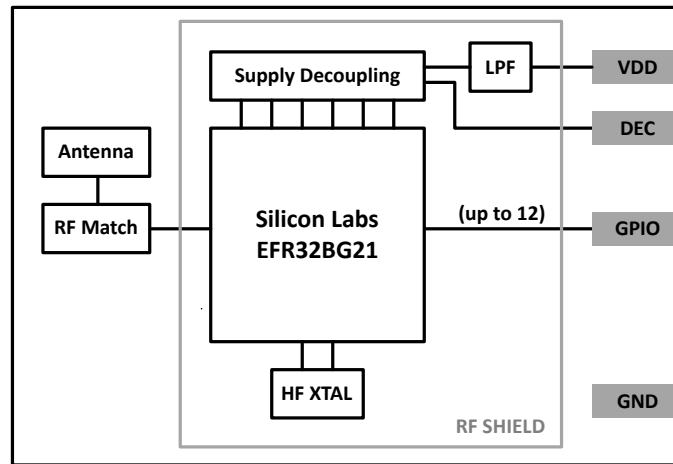


Figure 3.1. BGM210L Block Diagram

3.2 EFR32BG21 SoC

The EFR32BG21 SoC features a 32-bit ARM Cortex M33 core, a 2.4 GHz high-performance radio, 1 MB of Flash memory, a dedicated core for security, a rich set of MCU peripherals, and various clock management and serial interfacing options. Consult the [EFR32xG21 Wireless Gecko Reference Manual](#) and the [EFR32BG21 Data Sheet](#) for details (See EFR32BG21A020F1024IM32).

3.3 Antenna

BGM210L modules include a built-in PCB trace antenna with the characteristics seen below. The design of the antenna is optimized to operate the module mounted on an application board with a thickness of 0.8 mm.

Table 3.1. Antenna Efficiency and Peak Gain

Parameter	With optimal layout	Note
Efficiency	-2 to -2.5 dB	Antenna efficiency, gain and radiation pattern are highly dependent on the application PCB layout and mechanical design. Refer to 7. Design Guidelines for PCB layout and antenna integration guidelines for optimal performance.
Peak gain	0.5 dBi	

3.4 Power Supply

The BGM210L requires a single nominal supply level of 3.0 V. All the necessary decoupling and filtering components are included in the module. The module can tolerate supply voltage noise of up to 700 mVpp.

The supply voltage is filtered internally in the module with a 100 kHz low-pass filter to guarantee operation across the full supply range of 1.8 to 3.8 V. Additional external filtering is neither required nor recommended as it may cause voltage drops below the minimum level tolerable by the SoC (1.71 V) during transmit bursts.

For typical use cases, the decouple pin (DEC) should be left disconnected.

4. Electrical Specifications

4.1 Electrical Characteristics

All electrical parameters in all tables are specified under the following conditions, unless stated otherwise:

- Typical values are based on $T_A=25^\circ\text{C}$ and $V_{DD} = 3.0\text{ V}$, by production test and/or technology characterization.
- Radio performance numbers are measured in conducted mode, based on Silicon Laboratories reference designs using output power-specific external RF impedance-matching networks for interfacing to a $50\ \Omega$ antenna.
- Minimum and maximum values represent the worst conditions across supply voltage, process variation, and operating temperature, unless stated otherwise.

4.1.1 Absolute Maximum Ratings

Stresses above those listed below may cause permanent damage to the device. This is a stress rating only and functional operation of the devices at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability. For more information on the available quality and reliability data, see the Quality and Reliability Monitor Report at <http://www.silabs.com/support/quality/pages/default.aspx>.

Table 4.1. Absolute Maximum Ratings

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Storage temperature range	T_{STG}		-50	—	+150	$^\circ\text{C}$
Voltage on VDD supply pin	V_{DDMAX}		-0.3	—	3.8	V
Voltage ramp rate on VDD supply pin	$V_{DDRAMPMAX}$		—	—	1.0	V / μs
DC voltage on any GPIO pin	V_{DIGPIN}		-0.3	—	$V_{DD} + 0.3$	V
Total current into VDD pin	I_{VDDMAX}	Source	—	—	200	mA
Total current into GND pin	I_{GNDMAX}	Sink	—	—	200	mA
Current per I/O pin	I_{IOMAX}	Sink	—	—	50	mA
		Source	—	—	50	mA
Current for all I/O pins	$I_{IOALLMAX}$	Sink	—	—	200	mA
		Source	—	—	200	mA
Junction temperature	T_{JMAX}		—	—	+125	$^\circ\text{C}$

4.1.2 General Operating Conditions

This table specifies the general operating temperature range and supply voltage range for all supplies. The minimum and maximum values of all other tables are specified over this operating range, unless otherwise noted.

Table 4.2. General Operating Conditions

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Operating ambient temperature range	T _A	-N temperature grade	-40	—	+105	°C
		-I temperature grade	-40	—	+125	°C
VDD Supply Voltage	V _{DD}		1.8	3.0	3.8	V
HCLK and Core frequency	f _{HCLK}	MODE = WS1, RAMWSEN = 1 ¹	—	—	80	MHz
		MODE = WS1, RAMWSEN = 0 ¹	—	—	50	MHz
		MODE = WS0, RAMWSEN = 0 ¹	—	—	39	MHz
PCLK frequency	f _{PCLK}		—	—	50	MHz
EM01 Group A clock frequency	f _{EM01GRPACLK}		—	—	80	MHz
HCLK Radio frequency	f _{HCLKRADIO}		—	38.4	—	MHz

Note:

- Flash wait states are set by the MODE field in the MSC_READCTRL register. RAM wait states are enabled by setting the RAMWSEN bit in the SYSYCFG_DMEMP0RAMCTRL register.

4.1.3 MCU Current Consumption at 3.0V

Unless otherwise indicated, typical conditions are: VDD = 3.0 V. T_A = 25 °C. Minimum and maximum values in this table represent the worst conditions across process variation at T_A = 25 °C.

Table 4.3. MCU Current Consumption at 3.0V

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Current consumption in EM0 mode with all peripherals disabled ¹	I _{ACTIVE}	80 MHz HFRCO, CPU running Prime from flash	—	50.9	—	µA/MHz
		80 MHz HFRCO, CPU running while loop from flash	—	45.6	55.5	µA/MHz
		80 MHz HFRCO, CPU running CoreMark loop from flash	—	59.8	—	µA/MHz
		38.4 MHz crystal, CPU running while loop from flash	—	63.8	—	µA/MHz
Current consumption in EM1 mode with all peripherals disabled ¹	I _{EM1}	80 MHz HFRCO	—	28.7	37.6	µA/MHz
		38.4 MHz crystal	—	46.9	—	µA/MHz
Current consumption in EM2 mode	I _{EM2}	Full RAM retention and RTC running from LFXO (Bluetooth Stack not running)	—	5.1	—	µA
		Full RAM retention, RTCC running, and Bluetooth Stack running from LFXO	—	8.5	—	µA
		1 bank (16 kB) RAM retention and RTC running from LFRCO	—	4.5	10.5	µA
Current consumption in EM3 mode	I _{EM3}	Full RAM retention and RTC running from ULFRCO	—	4.8	11.4	µA
		1 bank (16 kB) RAM retention and RTC running from ULFRCO	—	4.3	—	µA
Current consumption in EM4 mode	I _{EM4}	No BURTC, no LF oscillator	—	0.21	0.5	µA
Current consumption during reset	I _{RST}	Hard pin reset held	—	146	—	µA
Current consumption per retained 16kB RAM bank in EM2	I _{RAM}		—	0.10	—	µA

Note:

1. The typical EM0/EM1 current measurement includes some current consumed by the security core for periodical housekeeping purposes. This does not include current consumed by user-triggered security operations, such as cryptographic calculations.

4.1.4 Radio Current Consumption at 3.0V

RF current consumption measured with MCU in EM1, HCLK = 38.4 MHz, and all MCU peripherals disabled. Unless otherwise indicated, typical conditions are: VDD = 3.0V. T_A = 25 °C. Minimum and maximum values in this table represent the worst conditions across process variation at T_A = 25 °C.

Table 4.4. Radio Current Consumption at 3.0V

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Current consumption in receive mode, active packet reception	I _{RX_ACTIVE}	125 kbit/s, 2GFSK, f = 2.4 GHz, Bluetooth stack running	—	9.3	—	mA
		500 kbit/s, 2GFSK, f = 2.4 GHz, Bluetooth stack running	—	9.3	—	mA
		1 Mbit/s, 2GFSK, f = 2.4 GHz, Bluetooth stack running	—	9.3	—	mA
		2 Mbit/s, 2GFSK, f = 2.4 GHz, Bluetooth stack running	—	9.9	—	mA
Current consumption in receive mode, Stack running	I _{RX_LISTEN}	125 kbit/s, 2GFSK, f = 2.4 GHz, Bluetooth stack running	—	9.1	—	mA
		500 kbit/s, 2GFSK, f = 2.4 GHz, Bluetooth stack running	—	9.1	—	mA
		1 Mbit/s, 2GFSK, f = 2.4 GHz, Bluetooth stack running	—	9.1	—	mA
		2 Mbit/s, 2GFSK, f = 2.4 GHz, Bluetooth stack running	—	9.8	—	mA
Current consumption in transmit mode	I _{TX}	f = 2.4 GHz, CW, 12.5 dBm output power, VDD = 3.3 V	—	70	—	mA

4.1.5 RF Transmitter General Characteristics for the 2.4 GHz Band

Unless otherwise indicated, typical conditions are: $T_A = 25\text{ }^{\circ}\text{C}$, $V_{DD} = 3.0\text{V}$. RF center frequency 2.45 GHz. ¹

Table 4.5. RF Transmitter General Characteristics for the 2.4 GHz Band

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
RF tuning frequency range	F_{RANGE}		2400	—	2483.5	MHz
Maximum TX power ²³	$POUT_{\text{MAX}}$	12 dBm PA, $V_{DD} = 3.3\text{ V}$	—	12.5	—	dBm
Minimum active TX Power	$POUT_{\text{MIN}}$	12 dBm PA, $V_{DD} = 3.3\text{ V}$	—	TBD	—	dBm
Output power variation vs VDD supply voltage variation, frequency = 2450MHz	$POUT_{\text{VAR_V}}$	12 dBm PA $P_{\text{out}} = POUT_{\text{MAX}}$ output power with VDD voltage swept from 3.8V to 3.0V.	—	+/- 0.5	—	dB
		12 dBm PA $P_{\text{out}} = POUT_{\text{MAX}}$ output power with VDD voltage swept from 3.8V to 1.8V	—	+0.5/-4.5	—	dB
Output power variation vs RF frequency	$POUT_{\text{VAR_F}}$	12 dBm PA, $POUT_{\text{MAX}}$, $V_{DD} = 3.3\text{ V}$.	—	+/- 0.1	—	dB

Note:

1. For regulatory compliance please refer to the official certification test reports
2. Supported transmit power levels are determined by the ordering part number (OPN). Transmit power ratings for all devices covered in this data sheet can be found in the TX Power column of the Ordering Information Table.
3. The maximum TXP to comply with ETSI PSD and EIRP limits depend on antenna gain which in turn depend on the end product mechanical design. In optimal conditions the module is compliant to the ETSI PSD and EIRP limits at maximum TXP of 8.2 dBm. End product manufacturer must ensure compliance to the limits for CE marking of the end product.

4.1.6 RF Receiver General Characteristics for the 2.4 GHz Band

Unless otherwise indicated, typical conditions are: $T_A = 25\text{ }^{\circ}\text{C}$, $V_{DD} = 3.0\text{V}$. RF center frequency 2.45 GHz.

Table 4.6. RF Receiver General Characteristics for the 2.4 GHz Band

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
RF tuning frequency range	F_{RANGE}		2400	—	2483.5	MHz

4.1.7 RF Receiver Characteristics for Bluetooth Low Energy at 1 Mbps

Unless otherwise indicated, typical conditions are: $T_A = 25\text{ }^{\circ}\text{C}$, $V_{DD} = 3.0\text{V}$. RF center frequency 2.45 GHz.

Table 4.7. RF Receiver Characteristics for Bluetooth Low Energy at 1 Mbps

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Max usable receiver input level	SAT	Signal is reference signal, packet length is 37 bytes ¹	—	10	—	dBm
Sensitivity	SENS	Signal is reference signal, 37 byte payload ¹	—	-97	—	dBm
		With non-ideal signals ^{2 1}	—	-96.5	—	dBm
Signal to co-channel interferer	C/I_{CC}	(see notes) ^{1 3}	—	+6.6	—	dB
$N \pm 1$ Adjacent channel selectivity	C/I_1	Interferer is reference signal at +1 MHz offset ^{1 4 3 5}	—	-8.3	—	dB
		Interferer is reference signal at -1 MHz offset ^{1 4 3 5}	—	-8.7	—	dB
$N \pm 2$ Alternate channel selectivity	C/I_2	Interferer is reference signal at +2 MHz offset ^{1 4 3 5}	—	-42.1	—	dB
		Interferer is reference signal at -2 MHz offset ^{1 4 3 5}	—	-48.9	—	dB
$N \pm 3$ Alternate channel selectivity	C/I_3	Interferer is reference signal at +3 MHz offset ^{1 4 3 5}	—	-42.4	—	dB
		Interferer is reference signal at -3 MHz offset ^{1 4 3 5}	—	-54.8	—	dB
Selectivity to image frequency	C/I_{IM}	Interferer is reference signal at image frequency with 1 MHz precision ^{1 5}	—	-42.1	—	dB
Selectivity to image frequency ± 1 MHz	C/I_{IM_1}	Interferer is reference signal at image frequency +1 MHz with 1 MHz precision ^{1 5}	—	-42.4	—	dB
		Interferer is reference signal at image frequency -1 MHz with 1 MHz precision ^{1 5}	—	-8.3	—	dB
Intermodulation performance	IM	$n = 3^6$	—	-23	—	dBm

Note:

1. 0.1% Bit Error Rate.
2. With non-ideal signals as specified in Bluetooth Test Specification RF-PHY.TS.5.0.1 section 4.7.1
3. Desired signal -67 dBm.
4. Desired frequency $2402\text{ MHz} \leq F_c \leq 2480\text{ MHz}$.
5. With allowed exceptions.
6. As specified in Bluetooth Core specification version 5.1, Vol 6, Part A, Section 4.4

4.1.8 RF Receiver Characteristics for Bluetooth Low Energy at 2 Mbps

Unless otherwise indicated, typical conditions are: $T_A = 25\text{ }^{\circ}\text{C}$, $V_{DD} = 3.0\text{V}$. RF center frequency 2.45 GHz.

Table 4.8. RF Receiver Characteristics for Bluetooth Low Energy at 2 Mbps

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Max usable receiver input level	SAT	Signal is reference signal, packet length is 37 bytes ¹	—	10	—	dBm
Sensitivity	SENS	Signal is reference signal, 37 byte payload ¹	—	-93.9	—	dBm
		With non-ideal signals ^{2 1}	—	-93.4	—	dBm
Signal to co-channel interferer	C/I_{CC}	(see notes) ^{1 3}	—	+6.0	—	dB
$N \pm 1$ Adjacent channel selectivity	C/I_1	Interferer is reference signal at +2 MHz offset ^{1 4 3 5}	—	-8.0	—	dB
		Interferer is reference signal at -2 MHz offset ^{1 4 3 5}	—	-8.8	—	dB
$N \pm 2$ Alternate channel selectivity	C/I_2	Interferer is reference signal at +4 MHz offset ^{1 4 3 5}	—	-42.2	—	dB
		Interferer is reference signal at -4 MHz offset ^{1 4 3 5}	—	-50.3	—	dB
$N \pm 3$ Alternate channel selectivity	C/I_3	Interferer is reference signal at +6 MHz offset ^{1 4 3 5}	—	-54.4	—	dB
		Interferer is reference signal at -6 MHz offset ^{1 4 3 5}	—	-55.4	—	dB
Selectivity to image frequency	C/I_{IM}	Interferer is reference signal at image frequency with 1 MHz precision ^{1 5}	—	-8.0	—	dB
Selectivity to image frequency ± 1 MHz	C/I_{IM_1}	Interferer is reference signal at image frequency +2 MHz with 1 MHz precision ^{1 5}	—	-42.2	—	dB
		Interferer is reference signal at image frequency -2 MHz with 1 MHz precision ^{1 5}	—	+6.0	—	dB
Intermodulation performance	IM	$n = 3^6$	—	-22.3	—	dBm

Note:

1. 0.1% Bit Error Rate.
2. With non-ideal signals as specified in Bluetooth Test Specification RF-PHY.TS.5.0.1 section 4.7.1
3. Desired signal -67 dBm.
4. Desired frequency $2402\text{ MHz} \leq F_c \leq 2480\text{ MHz}$.
5. With allowed exceptions.
6. As specified in Bluetooth Core specification version 5.1, Vol 6, Part A, Section 4.4

4.1.9 RF Receiver Characteristics for Bluetooth Low Energy at 500 kbps

Unless otherwise indicated, typical conditions are: $T_A = 25\text{ }^{\circ}\text{C}$, $V_{DD} = 3.0\text{V}$. RF center frequency 2.45 GHz.

Table 4.9. RF Receiver Characteristics for Bluetooth Low Energy at 500 kbps

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Max usable receiver input level	SAT	Signal is reference signal, packet length is 37 bytes ¹	—	10	—	dBm
Sensitivity	SENS	Signal is reference signal ¹	—	-100.1	—	dBm
		With non-ideal signals ^{2 1}	—	-99.5	—	dBm
Signal to co-channel interferer	C/I_{CC}	(see notes) ^{1 3}	—	+2.1	—	dB
$N \pm 1$ Adjacent channel selectivity	C/I_1	Interferer is reference signal at +1 MHz offset ^{1 4 3 5}	—	-9.0	—	dB
		Interferer is reference signal at -1 MHz offset ^{1 4 3 5}	—	-9.5	—	dB
$N \pm 2$ Alternate channel selectivity	C/I_2	Interferer is reference signal at +2 MHz offset ^{1 4 3 5}	—	-44.4	—	dB
		Interferer is reference signal at -2 MHz offset ^{1 4 3 5}	—	-51.9	—	dB
$N \pm 3$ Alternate channel selectivity	C/I_3	Interferer is reference signal at +3 MHz offset ^{1 4 3 5}	—	-44.3	—	dB
		Interferer is reference signal at -3 MHz offset ^{1 4 3 5}	—	-58.3	—	dB
Selectivity to image frequency	C/I_{IM}	Interferer is reference signal at image frequency with 1 MHz precision ^{1 5}	—	-44.4	—	dB
Selectivity to image frequency ± 1 MHz	C/I_{IM_1}	Interferer is reference signal at image frequency +1 MHz with 1 MHz precision ^{1 5}	—	-44.3	—	dB
		Interferer is reference signal at image frequency -1 MHz with 1 MHz precision ^{1 5}	—	-9.0	—	dB

Note:

1. 0.1% Bit Error Rate.
2. With non-ideal signals as specified in Bluetooth Test Specification RF-PHY.TS.5.0.1 section 4.7.1
3. Desired signal -72 dBm.
4. Desired frequency $2402\text{ MHz} \leq F_c \leq 2480\text{ MHz}$.
5. With allowed exceptions.

4.1.10 RF Receiver Characteristics for Bluetooth Low Energy at 125 kbps

Unless otherwise indicated, typical conditions are: $T_A = 25\text{ }^{\circ}\text{C}$, $V_{DD} = 3.0\text{V}$. RF center frequency 2.45 GHz.

Table 4.10. RF Receiver Characteristics for Bluetooth Low Energy at 125 kbps

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Max usable receiver input level	SAT	Signal is reference signal, packet length is 37 bytes ¹	—	10	—	dBm
Sensitivity	SENS	Signal is reference signal ¹	—	-104.4	—	dBm
		With non-ideal signals ^{2 1}	—	-104.1	—	dBm
Signal to co-channel interferer	C/I_{CC}	(see notes) ^{1 3}	—	+0.8	—	dB
$N \pm 1$ Adjacent channel selectivity	C/I_1	Interferer is reference signal at +1 MHz offset ^{1 4 3 5}	—	-13.1	—	dB
		Interferer is reference signal at -1 MHz offset ^{1 4 3 5}	—	-13.6	—	dB
$N \pm 2$ Alternate channel selectivity	C/I_2	Interferer is reference signal at +2 MHz offset ^{1 4 3 5}	—	-49.5	—	dB
		Interferer is reference signal at -2 MHz offset ^{1 4 3 5}	—	-56.9	—	dB
$N \pm 3$ Alternate channel selectivity	C/I_3	Interferer is reference signal at +3 MHz offset ^{1 4 3 5}	—	-47.0	—	dB
		Interferer is reference signal at -3 MHz offset ^{1 4 3 5}	—	-63.1	—	dB
Selectivity to image frequency	C/I_{IM}	Interferer is reference signal at image frequency with 1 MHz precision ^{1 5}	—	-49.5	—	dB
Selectivity to image frequency ± 1 MHz	C/I_{IM_1}	Interferer is reference signal at image frequency +1 MHz with 1 MHz precision ^{1 5}	—	-47.0	—	dB
		Interferer is reference signal at image frequency -1 MHz with 1 MHz precision ^{1 5}	—	-13.1	—	dB

Note:

1. 0.1% Bit Error Rate.
2. With non-ideal signals as specified in Bluetooth Test Specification RF-PHY.TS.5.0.1 section 4.7.1
3. Desired signal -79 dBm.
4. Desired frequency $2402\text{ MHz} \leq F_c \leq 2480\text{ MHz}$.
5. With allowed exceptions.

4.1.11 High-Frequency Crystal

Table 4.11. High-Frequency Crystal

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Crystal frequency	$f_{\text{HFX TAL}}$		—	38.4	—	MHz
Initial calibrated accuracy	$\text{ACC}_{\text{HFX TAL}}$		-10	—	+10	ppm
Temperature drift	$\text{DRIFT}_{\text{HFX TAL}}$	Across specified temperature range	-30	—	+30	ppm

4.1.12 GPIO Pins

Unless otherwise indicated, typical conditions are: VDD = 3.0 V.

Table 4.12. GPIO Pins

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Leakage current	$I_{\text{LEAK_IO}}$	MODEx = DISABLED, VDD = 1.71V	—	1.9	—	nA
		MODEx = DISABLED, VDD = 3.0 V	—	2.5	—	nA
Input low voltage ¹	V_{IL}	Any GPIO pin	—	—	0.3 * VDD	V
Input high voltage ¹	V_{IH}	Any GPIO pin	0.7 * VDD	—	—	V
Output low voltage	V_{OL}	Sinking 20mA, VDD = 3.0 V	—	—	0.2 * VDD	V
		Sinking 8mA, VDD = 1.62 V	—	—	0.4 * VDD	V
Output high voltage	V_{OH}	Sourcing 20mA, VDD = 3.0 V	0.8 * VDD	—	—	V
		Sourcing 8mA, VDD = 1.62 V	0.6 * VDD	—	—	V
GPIO rise time	$T_{\text{GPIO_RISE}}$	VDD = 3.0V, C_{load} = 50pF, SLEW-RATE = 4, 10% to 90%	—	8.4	—	ns
		VDD = 1.7V, C_{load} = 50pF, SLEW-RATE = 4, 10% to 90%	—	13	—	ns
GPIO fall time	$T_{\text{GPIO_FALL}}$	VDD = 3.0V, C_{load} = 50pF, SLEW-RATE = 4, 90% to 10%	—	7.1	—	ns
		VDD = 1.7V, C_{load} = 50pF, SLEW-RATE = 4, 90% to 10%	—	11.9	—	ns
Pull up/down resistance ²	R_{PULL}	pull-up: MODEn = DISABLE DOUT=1, pull-down: MODEn = WIREORPULLDOWN DOUT = 0	35	44	55	kΩ
Maximum filtered glitch width	T_{GF}	MODE = INPUT, DOUT = 1	—	26	—	ns

Note:

1. GPIO and RESETn input thresholds are proportional to the VDD supply.
2. GPIO and RESETn pull-ups connect to the VDD supply. Pull-downs on GPIO connect to VSS.

4.1.13 Microcontroller Peripherals

The MCU peripherals set available in BGM210L modules includes:

- 12-bit 1 Msps ADC
- Analog Comparators
- 16-bit and 32-bit Timers/Counters
- 24-bit Low Energy Timer for waveform generation
- 32-bit Real Time Counter
- USART (UART/SPI/SmartCards/IrDA/I2S)
- I²C peripheral interfaces
- 12 Channel Peripheral Reflex System

For details on their electrical performance, consult the relevant portions of Section 4 in the SoC datasheet.

To learn which GPIO ports provide access to every peripheral, consult [6.3 Analog Peripheral Connectivity](#) and [6.4 Digital Peripheral Connectivity](#).

4.2 Typical Performance Curves

Typical performance curves indicate typical characterized performance under the stated conditions.

4.2.1 Antenna Radiation and Efficiency

Typical BGM210L antenna radiation patterns and efficiency under optimal operating conditions are plotted in the figure below. Antenna gain and radiation patterns have a strong dependence on the size and shape of the application PCB the module is mounted on and, also, on the proximity of any mechanical design to the antenna.

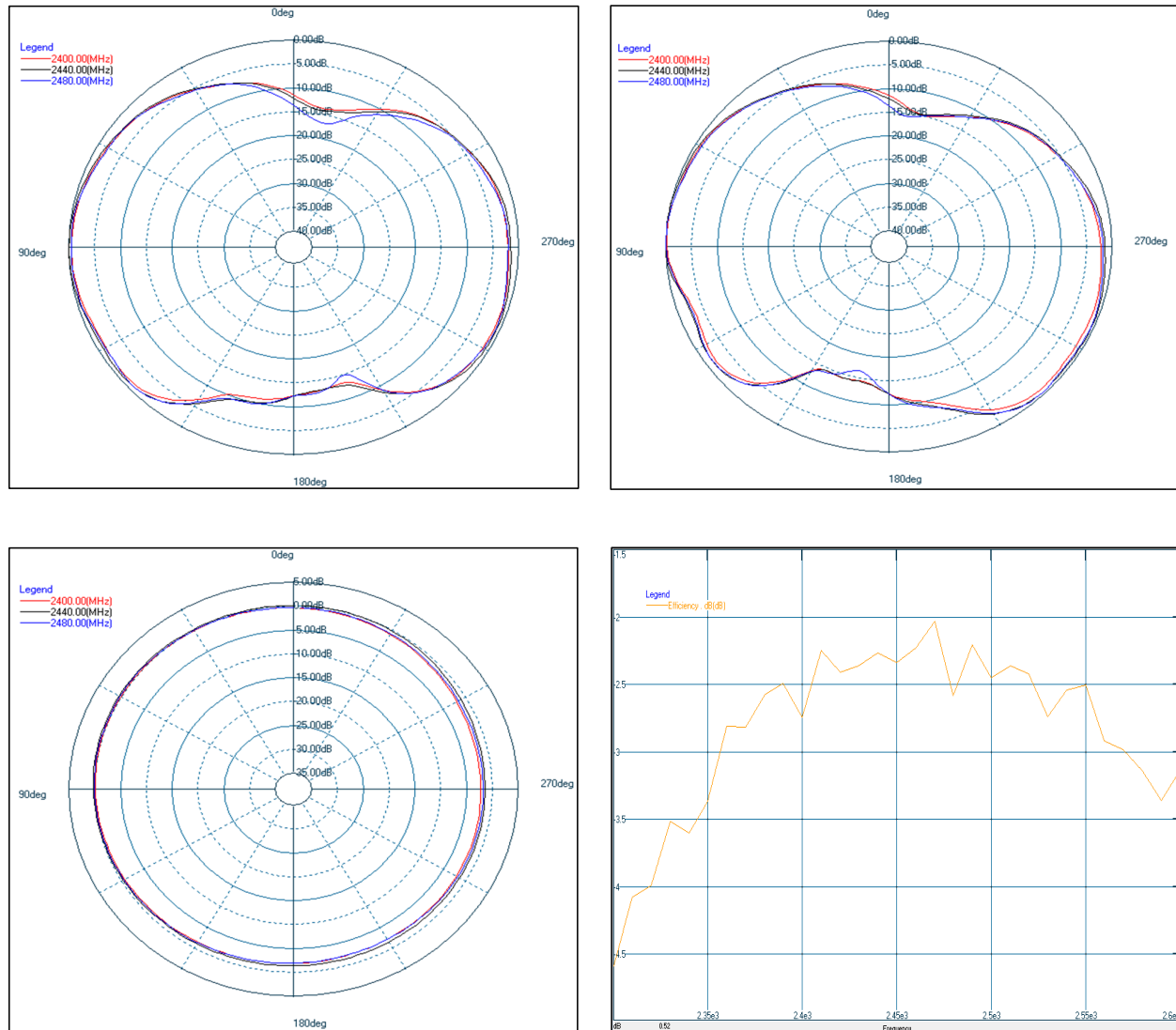


Figure 4.1. Typical 2D Antenna Radiation Patterns and Efficiency

Top Left: Phi 0°, Top Right: Phi 90°, Bottom Left: Theta 90°, Bottom Right: Radiation Efficiency

5. Reference Diagrams

A typical application circuit for the BGM210L module is shown below.

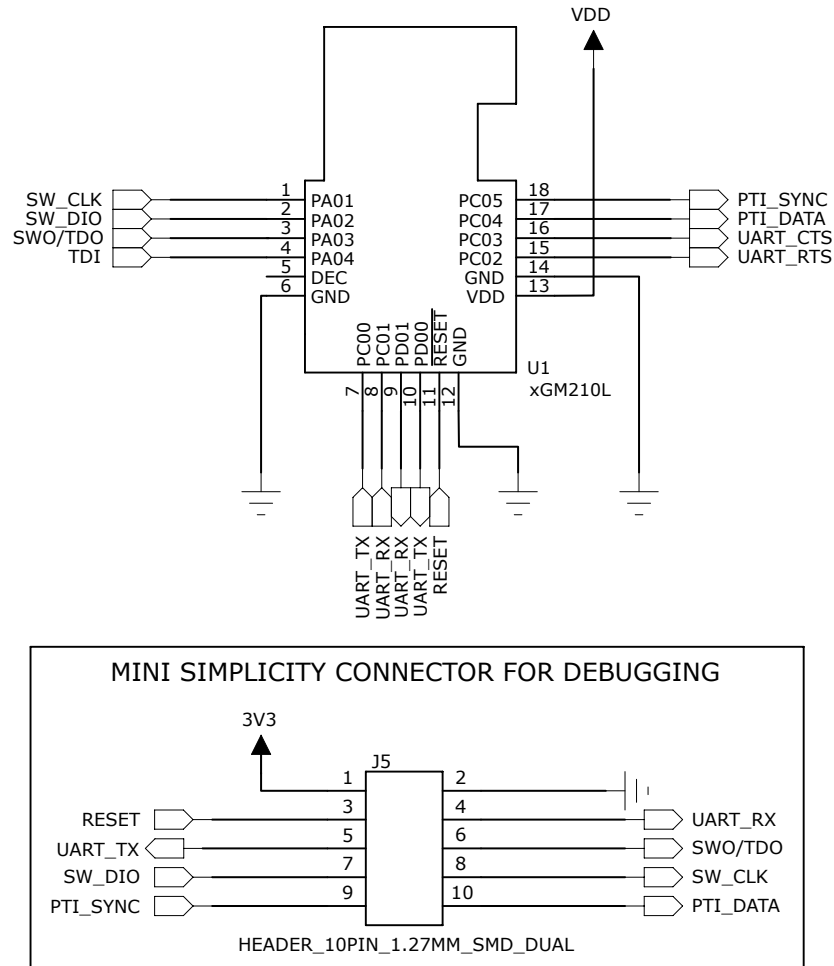


Figure 5.1. BGM210L Application Schematic

6. Pin Definitions

6.1 Module Pinout

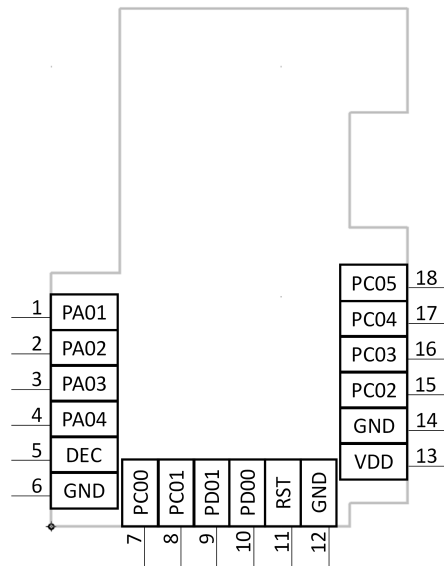


Figure 6.1. BGM210L Lighting Module Pinout

The next table shows the BGM210L pinout and some general descriptions of pin functionality. For more information on the features supported by each GPIO pin, see [6.3 Analog Peripheral Connectivity](#) and [6.4 Digital Peripheral Connectivity](#).

Table 6.1. BGM210L Lighting Module Pin Definitions

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PA01	1	PA01/SWCLK (Serial Wire Clock)	PA02	2	PA02/SWDIO (Serial Wire Data I/O)
PA03	3	PA03/SWV/TDO (Serial Wire Viewer)	PA04	4	PA04/TDI
DEC	5	Decouple ¹	GND	6	
PC00	7	PC00/PTI_SYNC (PTI Sync Out)	PC01	8	PC01/PTI_DATA (PTI Data out)
PD01	9	GPIO	PD00	10	GPIO
RESETn	11	Reset Pin	GND	12	
VDD	13	VDD	GND	14	
PC02	15	GPIO ²	PC03	16	GPIO ²
PC04	17	GPIO ²	PC05	18	GPIO ²

Note:

1. Do not use Decouple supply to power external circuitry.
2. Internally terminated with series 56 ohm resistor.

6.2 Alternate Pin Functions

Some pins support multiple functions through internal multiplexing in the SoC (e.g. debugging, wake-up, etc.). The following table shows the functions available on each module pin. Refer to the SoC's reference manual for more details.

Table 6.2. GPIO Alternate Functions Table

GPIO	Alternate Function		
PA01	GPIO.SWCLK		
PA02	GPIO.SWDIO		
PA03	GPIO.SWV	GPIO.TDO	GPIO.TRACEDATA0
PA04	GPIO.TDI	GPIO.TRACECLK	
PC00	GPIO.EM4WU6		
PD01	LF XO.LFXTAL_I	LF XO.LF_EXTCLK	
PD00	LF XO.LFXTAL_O		
PC05	GPIO.EM4WU7		

6.3 Analog Peripheral Connectivity

Many analog resources are routable and can be connected to numerous GPIO's. The table below indicates which peripherals are available on each GPIO port. When a differential connection is being used Positive inputs are restricted to the EVEN pins and Negative inputs are restricted to the ODD pins. When a single ended connection is being used positive input is available on all pins. See the device Reference Manual for more details on the ABUS and analog peripherals.

Table 6.3. ABUS Routing Table

Peripheral	Signal	PA		PC		PD	
		EVEN	ODD	EVEN	ODD	EVEN	ODD
ACMP0	ana_neg	Yes	Yes	Yes	Yes	Yes	Yes
	ana_pos	Yes	Yes	Yes	Yes	Yes	Yes
ACMP1	ana_neg	Yes	Yes	Yes	Yes	Yes	Yes
	ana_pos	Yes	Yes	Yes	Yes	Yes	Yes
IADC0	ana_neg	Yes	Yes	Yes	Yes	Yes	Yes
	ana_pos	Yes	Yes	Yes	Yes	Yes	Yes

6.4 Digital Peripheral Connectivity

Many digital resources are routable and can be connected to numerous GPIO's. The table below indicates which peripherals are available on each GPIO port.

Table 6.4. DBUS Routing Table

Peripheral.Resource	PORT		
	PA	PC	PD
ACMP0.DIGOUT	Available	Available	Available
ACMP1.DIGOUT	Available	Available	Available
CMU.CLKIN0		Available	Available
CMU.CLKOUT0		Available	Available
CMU.CLKOUT1		Available	Available
CMU.CLKOUT2	Available		
FRC.DCLK		Available	Available
FRC.DFRAME		Available	Available
FRC.DOUT		Available	Available
I2C0.SCL	Available	Available	Available
I2C0.SDA	Available	Available	Available
I2C1.SCL		Available	Available
I2C1.SDA		Available	Available
LETIMER0.OUT0	Available		
LETIMER0.OUT1	Available		
PRS.ASYNCH0	Available		
PRS.ASYNCH1	Available		
PRS.ASYNCH10		Available	Available
PRS.ASYNCH11		Available	Available
PRS.ASYNCH2	Available		
PRS.ASYNCH3	Available		
PRS.ASYNCH4	Available		
PRS.ASYNCH5	Available		
PRS.ASYNCH6		Available	Available
PRS.ASYNCH7		Available	Available
PRS.ASYNCH8		Available	Available
PRS.ASYNCH9		Available	Available
PRS.SYNCH0	Available	Available	Available
PRS.SYNCH1	Available	Available	Available
PRS.SYNCH2	Available	Available	Available
PRS.SYNCH3	Available	Available	Available

Peripheral.Resource	PORT		
	PA	PC	PD
TIMER0.CC0	Available	Available	Available
TIMER0.CC1	Available	Available	Available
TIMER0.CC2	Available	Available	Available
TIMER0.CDTI0	Available	Available	Available
TIMER0.CDTI1	Available	Available	Available
TIMER0.CDTI2	Available	Available	Available
TIMER1.CC0	Available	Available	Available
TIMER1.CC1	Available	Available	Available
TIMER1.CC2	Available	Available	Available
TIMER1.CDTI0	Available	Available	Available
TIMER1.CDTI1	Available	Available	Available
TIMER1.CDTI2	Available	Available	Available
TIMER2.CC0	Available		
TIMER2.CC1	Available		
TIMER2.CC2	Available		
TIMER2.CDTI0	Available		
TIMER2.CDTI1	Available		
TIMER2.CDTI2	Available		
TIMER3.CC0		Available	Available
TIMER3.CC1		Available	Available
TIMER3.CC2		Available	Available
TIMER3.CDTI0		Available	Available
TIMER3.CDTI1		Available	Available
TIMER3.CDTI2		Available	Available
USART0.CLK	Available	Available	Available
USART0.CS	Available	Available	Available
USART0.CTS	Available	Available	Available
USART0.RTS	Available	Available	Available
USART0.RX	Available	Available	Available
USART0.TX	Available	Available	Available
USART1.CLK	Available		
USART1.CS	Available		
USART1.CTS	Available		
USART1.RTS	Available		
USART1.RX	Available		
USART1.TX	Available		

Peripheral.Resource	PORT		
	PA	PC	PD
USART2.CLK		Available	Available
USART2.CS		Available	Available
USART2.CTS		Available	Available
USART2.RTS		Available	Available
USART2.RX		Available	Available
USART2.TX		Available	Available

7. Design Guidelines

7.1 Module Placement

The BGM210L should be placed at the edge of the end-application PCB as seen below. The copper clearance area under the antenna must be void of traces or components to prevent parasitic loading or undesired coupling of signals or noise to the antenna.

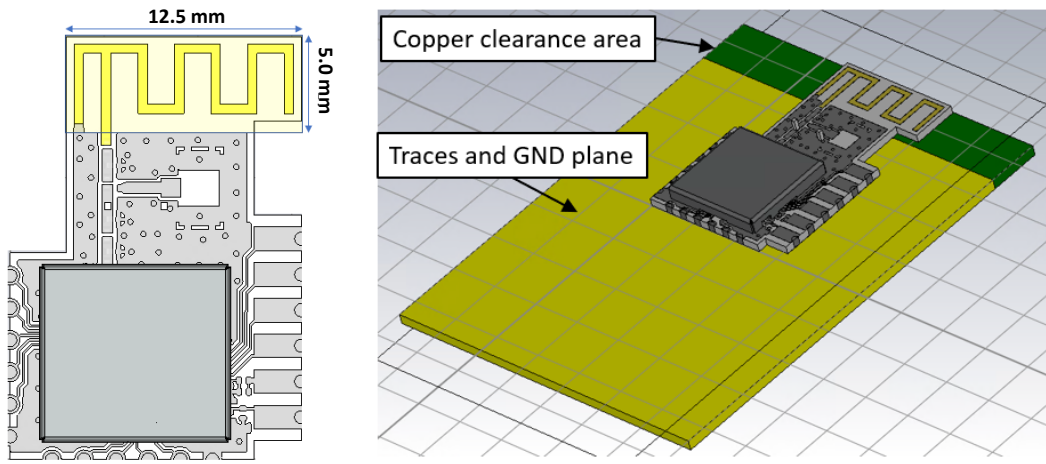


Figure 7.1. Inverted-F Antenna Clearance

Figure 7.2 Horizontal Mounting on page 25 illustrates the placement recommended when mounting the module horizontally to an end-application PCB. It also shows examples of layout cases that will result in severe RF performance degradation for the module.

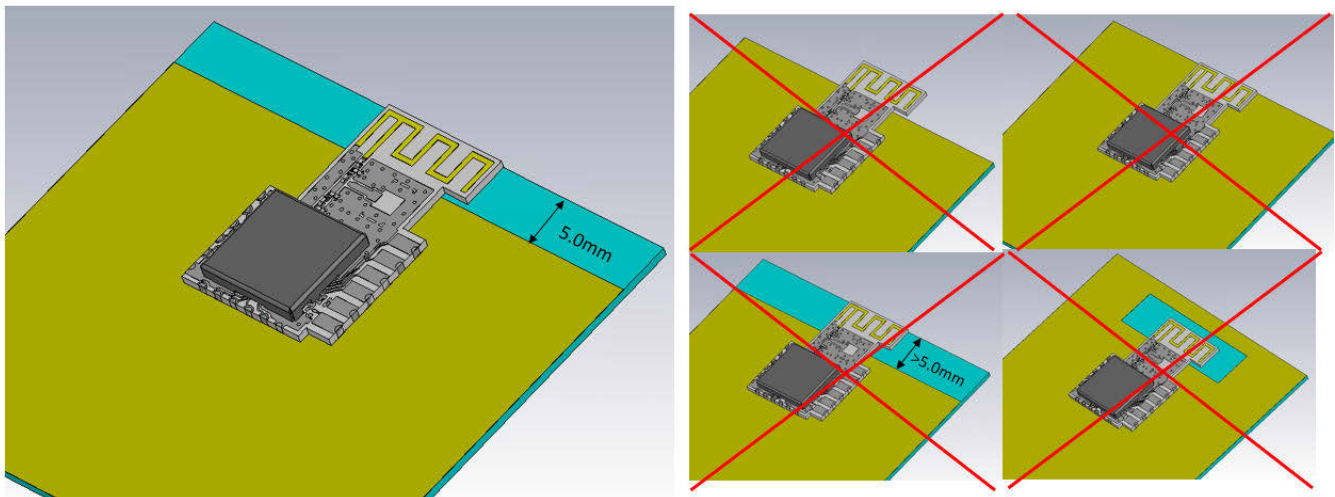


Figure 7.2. Horizontal Mounting

Figure 7.3 Vertical Mounting on page 26 illustrates the placement recommended when mounting the module vertically to an end-application PCB. It also shows examples of layout cases that will result in severe RF performance degradation for the module.

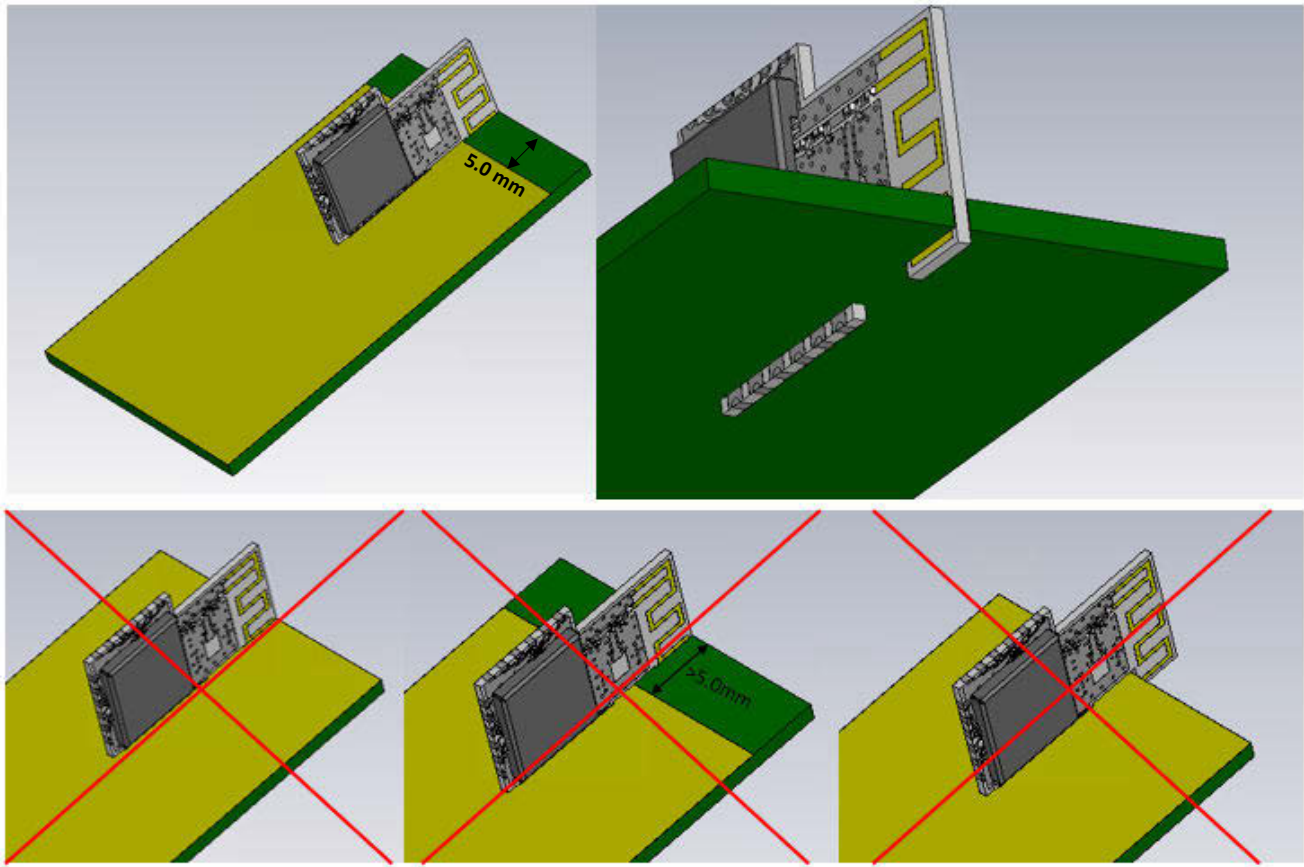


Figure 7.3. Vertical Mounting

The size and shape of the application PCB have an impact on the radiation patterns and radiation efficiency of the antenna. Metal objects in close proximity to the antenna will have a negative impact on its radiation efficiency.

7.2 Antenna

Due to the nature of inverted-F PCB antennas, the BGM210L is sensitive to the thickness of the application PCB on which it is mounted, as well as to any plastics, metal or dielectric materials in close proximity to the antenna. The layout guide shown in [Figure 7.2 Horizontal Mounting on page 25](#) is optimized for an application board thickness of 0.8 mm.

For cases where the application board is of a thickness different than the optimal, the impedance and performance of the antenna can be adjusted and optimized by

1. Making a cutout to remove excessive FR4 material from underneath the antenna, or by
2. Moving the GND plane for the antenna either farther away or closer

In absence of a VNA, the antenna optimization may be verified by measuring RSSI or radiated output power until either is maximized.

8. Package Specifications

8.1 Dimensions

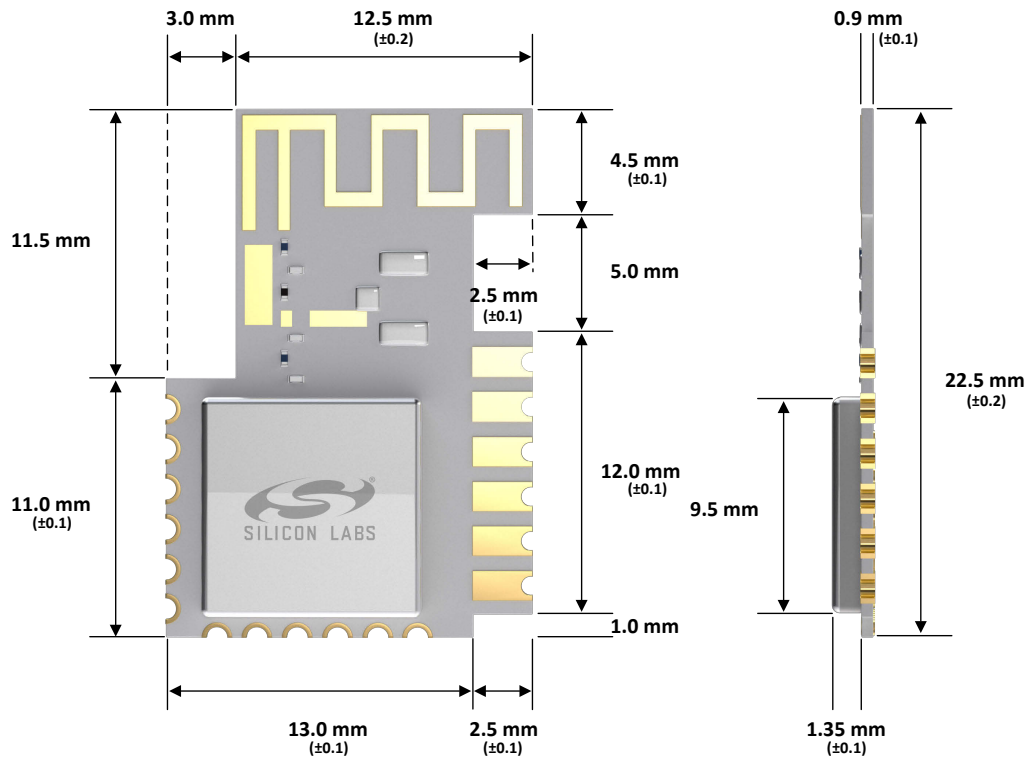


Figure 8.1. Module Dimensions

8.2 PCB Land Pattern

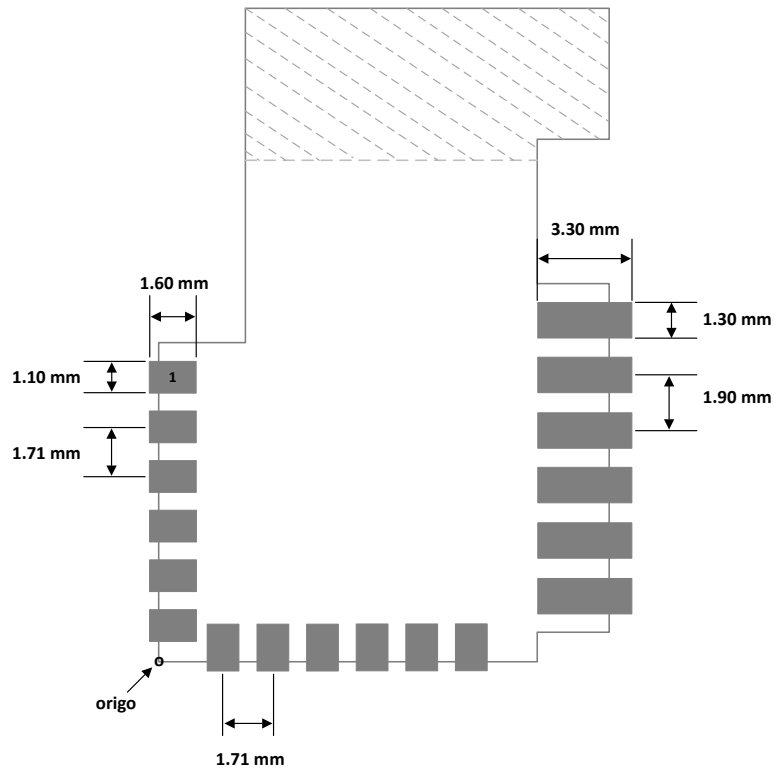


Figure 8.2. Recommended Module PCB Land Pattern

Table 8.1. Pad Sizing and Location

Pad Number	X Coordinate	Y Coordinate	Pad Dimensions
1	0.5	9.78	1.1 x 1.6
6	0.5	1.23	1.1 x 1.6
7	2.23	0.5	1.1 x 1.6
12	10.78	0.5	1.1 x 1.6
13	14.67	2.25	1.3 x 3.3
18	14.67	11.75	1.3 x 3.3

Note:

1. All dimensions in mm unless otherwise stated.
2. X and Y coordinates specified relative to origo at indicated package corner.
3. The module has a test point for VDD at (X=2.65, Y=6.45). To prevent the possibility of a short circuit, avoid leaving bare copper exposed at this location.

8.3 Marking

The figure below shows the markings engraved on the RF shield of the module.

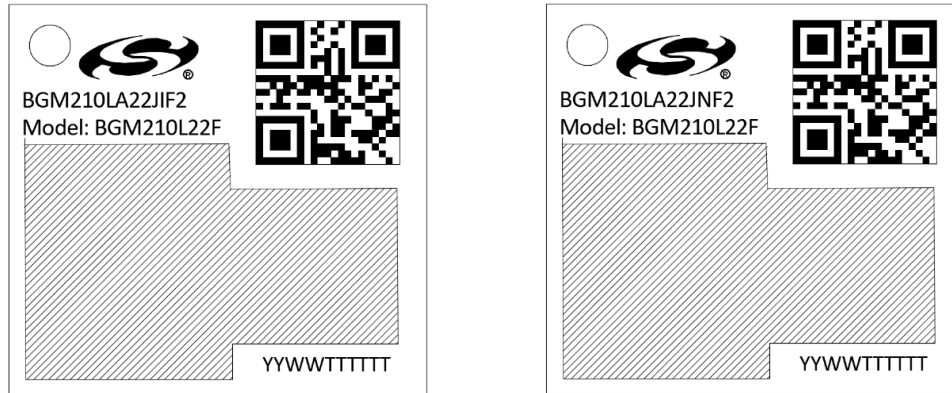


Figure 8.3. BGM210L Shield Marking

Mark Description

The module shield marking includes the following:

- BGM210Lxxxxxxx - Part number designation
- Model: BGM210L22F - Model number designation
- QR Code: YYWWMMABCDE
 - YY – Last two digits of the assembly year.
 - WW – Two-digit workweek when the device was assembled.
 - MMABCDE – Silicon Labs unit code
- YYWWTTTTTTT
 - YY – Last two digits of the assembly year.
 - WW – Two-digit workweek when the device was assembled.
 - TTTTTT – Manufacturing trace code. The first letter is the device revision.
- Certification marks such as the CE logo, FCC and IC IDs, etc. will be engraved in the dotted-line gray area according to regulatory body requirements, or printed on the back side of the module.

9. Soldering Recommendations

It is recommended that final PCB assembly of the BGM210L follows the industry standard as identified by the Institute for Printed Circuits (IPC). This product is assembled in compliance with the J-STD-001 requirements and the guidelines of IPC-AJ-820. Surface mounting of this product by the end user is recommended to follow IPC-A-610 to meet or exceed class 2 requirements.

CLASS 1 General Electronic Products

Includes products suitable for applications where the major requirement is function of the completed assembly.

CLASS 2 Dedicated Service Electronic Products

Includes products where continued performance and extended life is required, and for which uninterrupted service is desired but not critical. Typically the end-use environment would not cause failures.

CLASS 3 High Performance/Harsh Environment Electronic Products

Includes products where continued high performance or performance-on-demand is critical, equipment downtime cannot be tolerated, end-use environment may be uncommonly harsh, and the equipment must function when required, such as life support or other critical systems.

10. Tape and Reel

All dimensions are given in mm unless otherwise indicated.

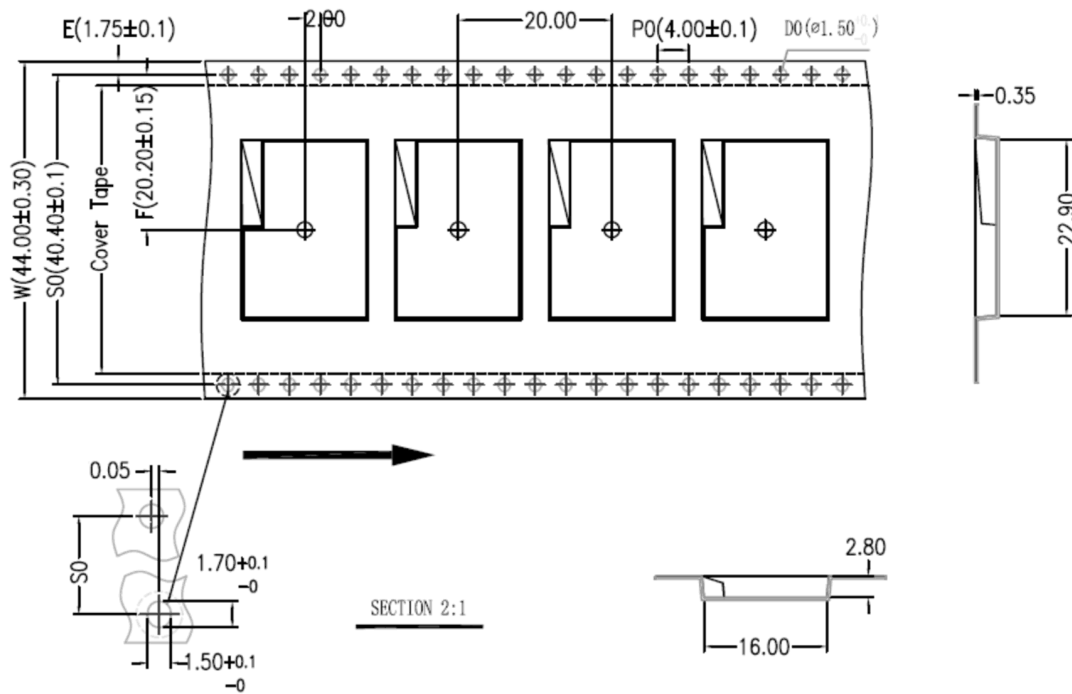


Figure 10.1. Carrier Tape Dimensions

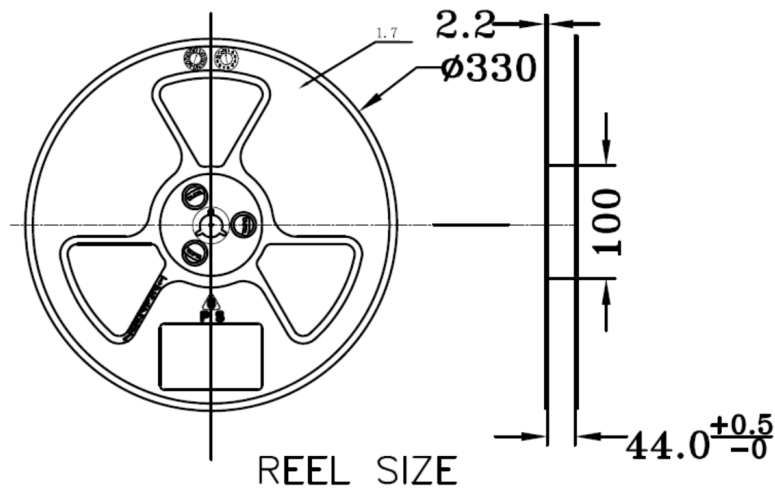


Figure 10.2. Reel Dimensions

11. Certifications

This section details the regulatory certification status of the module in various regions.

The address for the module manufacturer and certification applicant is:

SILICON LABORATORIES FINLAND OY
Alberga Business Park, Bertel Jungin aukio 3,
02600 Espoo, Finland

11.1 CE

The BGM210L module is in conformity with the essential requirements and other relevant requirements of the Radio Equipment Directive (RED) (2014/53/EU). Please note that every application using the BGM210L will need to perform the radio EMC tests on the end product, according to EN 301 489-17. It is ultimately the responsibility of the manufacturer to ensure the compliance of the end-product. The specific product assembly may have an impact to RF radiated characteristics, and manufacturers should carefully consider RF radiated testing with the end-product assembly. A formal Declaration of Conformity (DoC) is available via <https://www.silabs.com/>.

11.2 FCC

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions:

1. This device may not cause harmful interference, and
2. This device must accept any interference received, including interference that may cause undesirable operation.

Any changes or modifications not expressly approved by Silicon Labs could void the user's authority to operate the equipment.

FCC RF Radiation Exposure Statement:

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment. End users must follow the specific operating instructions for satisfying RF exposure compliance. This transmitter meets both portable and mobile requirements in accordance to the limits exposed in the RF Exposure Analysis. This transmitter must not be co-located or operating in conjunction with any other antenna or transmitter except in accordance with FCC multi-transmitter product procedures.

OEM Responsibilities to comply with FCC Regulations:

OEM integrator is responsible for testing their end-product for any additional compliance requirements needed with this module installed (for example, digital device emissions, PC peripheral requirements, etc.). Additionally, investigative measurements and spot checking are strongly recommended to verify that the full system compliance is maintained when the module is integrated, in accordance to the "Host Product Testing Guidance" in FCC's KDB 996369 D04 Module Integration Guide V01.

- In the typical case when the integral antenna of the BGM210L is used, a minimum separation distance of 12 mm must be maintained at all times between the human body and the radiator (antenna) to meet the SAR exemption for portable conditions.
- The transmitter module must not be co-located or operating in conjunction with any other antenna or transmitter except in accordance with FCC multi-transmitter product procedures.

Important Note:

In the event that these conditions cannot be met, then for the FCC authorization to remain valid the final product will have to undergo additional testing to evaluate the RF exposure, and a permissive change will have to be applied with the help of the customer's own Telecommunication Certification Body.

End Product Labeling

The variants of BGM210L Modules are labeled with their own FCC ID. If the FCC ID is not visible when the module is installed inside another device, then the outside of the device into which the module is installed must also display a label referring to the enclosed module. In that case, the final end product must be labeled in a visible area with the following:

"Contains Transmitter Module FCC ID: QOQMGM210L"

Or

"Contains FCC ID: QOQMGM210L"

The OEM integrator has to be aware not to provide information to the end user regarding how to install or remove this RF module or change RF related parameters in the user manual of the end product.

Class B Device Notice

Note: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna
- Increase the separation between the equipment and receiver
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected
- Consult the dealer or an experienced radio/TV technician for help

11.3 ISED Canada

ISED

This radio transmitter (IC: 5123A-MGM210L) has been approved by Industry Canada to operate with the embedded antenna. Any other antenna types are strictly prohibited for use with this device.

This device complies with Industry Canada's license-exempt RSS standards. Operation is subject to the following two conditions:

1. This device may not cause interference; and
2. This device must accept any interference, including interference that may cause undesired operation of the device

RF Exposure Statement

Exception from routine SAR evaluation limits are given in RSS-102 Issue 5.

The module meets the given requirements when the minimum separation distance to human body is 20 mm.

RF exposure or SAR evaluation is not required when the separation distance is same or more than stated above. If the separation distance is less than stated above the OEM integrator is responsible for evaluating the SAR.

OEM Responsibilities to comply with IC Regulations

The module has been certified for integration into products only by OEM integrators under the following conditions:

- The antenna must be installed such that a minimum separation distance as stated above is maintained between the radiator (antenna) and all persons at all times.
- The transmitter module must not be co-located or operating in conjunction with any other antenna or transmitter.

As long as the two conditions above are met, further transmitter testing will not be required. However, the OEM integrator is still responsible for testing their end-product for any additional compliance requirements required with this module installed (for example, digital device emissions, PC peripheral requirements, etc.).

IMPORTANT NOTE

In the event that these conditions cannot be met (for certain configurations or co-location with another transmitter), then the ISED authorization is no longer considered valid and the IC ID cannot be used on the final product. In these circumstances, the OEM integrator will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate ISED authorization.

End Product Labeling

The BGM210L module is labeled with its own IC ID. If the IC ID is not visible when the module is installed inside another device, then the outside of the device into which the module is installed must also display a label referring to the enclosed module. In that case, the final end product must be labeled in a visible area with the following:

"Contains Transmitter Module IC: 5123A-MGM210L "

or

"Contains IC: 5123A-MGM210L"

The OEM integrator has to be aware not to provide information to the end user regarding how to install or remove this RF module or change RF related parameters in the user manual of the end product.

ISED (Français)

Industrie Canada a approuvé l'utilisation de cet émetteur radio (IC: 5123A-MGM210L) en conjonction avec l'antenne intégrée. L'utilisation de tout autre type d'antenne avec ce composant est proscrite.

Ce composant est conforme aux normes RSS, exonérées de licence d'Industrie Canada. Son mode de fonctionnement est soumis aux deux conditions suivantes:

1. Ce composant ne doit pas générer d'interférences.
2. Ce composant doit pouvoir est soumis à tout type de perturbation y compris celle pouvant nuire à son bon fonctionnement.

Déclaration d'exposition RF

L'exception tirée des limites courantes d'évaluation SAR est donnée dans le document RSS-102 Issue 5.

Le module répondent aux exigences requises lorsque la distance minimale de séparation avec le corps humain est de 20 mm.

La déclaration d'exposition RF ou l'évaluation SAR n'est pas nécessaire lorsque la distance de séparation est identique ou supérieure à celle indiquée ci-dessus. Si la distance de séparation est inférieure à celle mentionnées plus haut, il incombe à l'intégrateur OEM de procéder à une évaluation SAR.

Responsabilités des OEM pour une mise en conformité avec le Règlement du Circuit Intégré

Le module a été approuvé pour l'intégration dans des produits finaux exclusivement réalisés par des OEM sous les conditions suivantes:

- L'antenne doit être installée de sorte qu'une distance de séparation minimale indiquée ci-dessus soit maintenue entre le radiateur (antenne) et toutes les personnes avoisinante, ce à tout moment.
- Le module émetteur ne doit pas être localisé ou fonctionner avec une autre antenne ou un autre transmetteur que celle indiquée plus haut.

Tant que les deux conditions ci-dessus sont respectées, il n'est pas nécessaire de tester ce transmetteur de façon plus poussée. Cependant, il incombe à l'intégrateur OEM de s'assurer de la bonne conformité du produit fini avec les autres normes auxquelles il pourrait être soumis de fait de l'utilisation de ce module (par exemple, les émissions des périphériques numériques, les exigences de périphériques PC, etc.).

REMARQUE IMPORTANTE

Ans le cas où ces conditions ne peuvent être satisfaites (pour certaines configurations ou co-implantation avec un autre émetteur), l'autorisation ISED n'est plus considérée comme valide et le numéro d'identification ID IC ne peut pas être apposé sur le produit final. Dans ces circonstances, l'intégrateur OEM sera responsable de la réévaluation du produit final (y compris le transmetteur) et de l'obtention d'une autorisation ISED distincte.

Étiquetage des produits finis

Les modules BGM210L sont étiquetés avec leur propre ID IC. Si l'ID IC n'est pas visible lorsque le module est intégré au sein d'un autre produit, cet autre produit dans lequel le module est installé devra porter une étiquette faisant apparaître les référence du module intégré. Dans un tel cas, sur le produit final doit se trouver une étiquette aisément lisible sur laquelle figurent les informations suivantes:

“Contient le module transmetteur: 5123A-MGM210L ”

or

“Contient le circuit: 5123A-MGM210L”

L'intégrateur OEM doit être conscient qu'il ne doit pas fournir, dans le manuel d'utilisation, d'informations relatives à la façon d'installer ou de d'enlever ce module RF ainsi que sur la procédure à suivre pour modifier les paramètres liés à la radio.

11.4 Australia

The BGM210L is compliant to Australian/New Zeland RCM requirements and the module is labeled with the RCM mark. The formal DoC is available at <https://www.silabs.com/>.

11.5 Dominican Republic

The BGM210L has type approval in the Dominican Republic. The formal type approval certificate is available at <https://www.silabs.com/>.

11.6 Hong Kong

The BGM210L has approval in Hong Kong. The formal type approval certificate is available at <https://www.silabs.com/>.



11.7 Israel

מספר אישור התאמה אלחוטי של משרד התקשורת הוא 51-68584
אסור להחליף את האנטנה המקורית של המכשיר ולא לעשות בו כל שינוי טכני אחר

11.8 Jordan

The BGM210L has type approval in Jordan with type approval number TRC/SS/2019/211. The type approval is valid until 06/05/2020.

11.9 Kuwait

The BGM210L has type approval in Kuwait. The formal type approval certificate is available at <https://www.silabs.com/>.

11.10 Serbia

The BGM210L has type approval in Serbia. The formal type approval certificate is available at <https://www.silabs.com/>.



11.11 Singapore

The BGM210L has been registered with the Info-communications Media Development Authority under regulation 20(6) of the Telecommunications (Dealers) Regulations (Cap 323, Rg 6) (the "Dealers Regulations") and approved for sale in Singapore. The registration number is N1436-19.

12. Revision History

Revision 0.5.1

September, 2019

- Updated [Ordering Information](#) with "210LA" OPNs
- Updated [Package Specifications](#) with corresponding "210LA" top mark figures

Revision 0.5

August, 2019

- Initial Production Release.
- Updated [Features](#) with latest values, certifications, security, etc
- Updated [Ordering Information](#) with OPNs for Reel packaging
- Added [System Overview](#)
- Updated [Electrical Specifications](#) with latest values
- Updated Tables 6.2 - 6.4 in [Pin Definitions](#)
- Updated wording and figures in [Design Guidelines](#)
- Updated figures in [Package Specifications](#) and added Marking section
- Added [Tape and Reel](#) dimensions
- Updated list of regions/countries in [Certifications](#)
- General wording, spelling, and grammar fixes.

Revision 0.2

July, 2019

- Updated typical specification values to reflect module measurements.
- Wording, spelling, and grammar fixes.

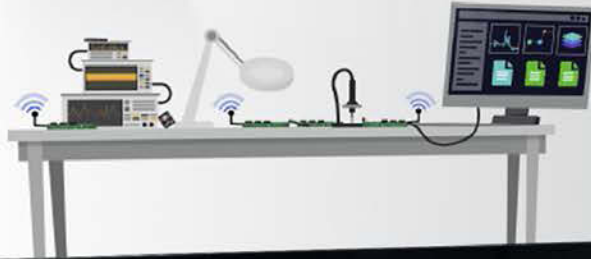
Revision 0.1

April, 2019

- Initial Release.

Silicon Labs

Simplicity Studio™4



Simplicity Studio

One-click access to MCU and wireless tools, documentation, software, source code libraries & more. Available for Windows, Mac and Linux!



IoT Portfolio
www.silabs.com/IoT



SW/HW
www.silabs.com/simplicity



Quality
www.silabs.com/quality



Support and Community
community.silabs.com

Disclaimer

Silicon Labs intends to provide customers with the latest, accurate, and in-depth documentation of all peripherals and modules available for system and software implementers using or intending to use the Silicon Labs products. Characterization data, available modules and peripherals, memory sizes and memory addresses refer to each specific device, and "Typical" parameters provided can and do vary in different applications. Application examples described herein are for illustrative purposes only. Silicon Labs reserves the right to make changes without further notice to the product information, specifications, and descriptions herein, and does not give warranties as to the accuracy or completeness of the included information. Without prior notification, Silicon Labs may update product firmware during the manufacturing process for security or reliability reasons. Such changes will not alter the specifications or the performance of the product. Silicon Labs shall have no liability for the consequences of use of the information supplied in this document. This document does not imply or expressly grant any license to design or fabricate any integrated circuits. The products are not designed or authorized to be used within any FDA Class III devices, applications for which FDA premarket approval is required or Life Support Systems without the specific written consent of Silicon Labs. A "Life Support System" is any product or system intended to support or sustain life and/or health, which, if it fails, can be reasonably expected to result in significant personal injury or death. Silicon Labs products are not designed or authorized for military applications. Silicon Labs products shall under no circumstances be used in weapons of mass destruction including (but not limited to) nuclear, biological or chemical weapons, or missiles capable of delivering such weapons. Silicon Labs disclaims all express and implied warranties and shall not be responsible or liable for any injuries or damages related to use of a Silicon Labs product in such unauthorized applications.

Trademark Information

Silicon Laboratories Inc.®, Silicon Laboratories®, Silicon Labs®, SiLabs® and the Silicon Labs logo®, Bluegiga®, Bluegiga Logo®, ClockBuilder®, CMEMS®, DSPLL®, EFM®, EFM32®, EFR, Ember®, Energy Micro, Energy Micro logo and combinations thereof, "the world's most energy friendly microcontrollers", Ember®, EZLink®, EZRadio®, EZRadioPRO®, Gecko®, Gecko OS, Gecko OS Studio, ISOmodem®, Precision32®, ProSLIC®, Simplicity Studio®, SiPHY®, Telegesis, the Telegesis Logo®, USBXpress®, Zentri, the Zentri logo and Zentri DMS, Z-Wave®, and others are trademarks or registered trademarks of Silicon Labs. ARM, CORTEX, Cortex-M3 and THUMB are trademarks or registered trademarks of ARM Holdings. Keil is a registered trademark of ARM Limited. Wi-Fi is a registered trademark of the Wi-Fi Alliance. All other products or brand names mentioned herein are trademarks of their respective holders.



Silicon Laboratories Inc.
400 West Cesar Chavez
Austin, TX 78701
USA

<http://www.silabs.com>